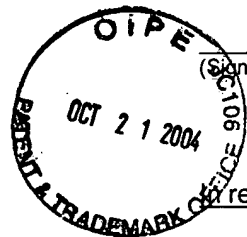


IFW

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to : Commissioner of Patents and Trademarks, p. o. Box 1450, ALEXANDRIA, VA 22313-1450, on October 19, 2004. The applicant and/or attorney requests the date of deposit as the filing date. Depositor: Nicole Barrese

Nicole Barrese 10-19-04  
(Signature & date)



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

re application of \_\_\_\_\_: October 19, 2004

Mukta Farooq, et al.

Serial No. 10/711,461:

Examiner: Not yet assigned

Filed: 9/20/04 :

International Business Machines Corporation  
2070 Route 52  
Hopewell Junction, NY 12533

**TITLE:**      STRUCTURE AND METHOD TO GAIN SUBSTANTIAL RELIABILITY  
IMPROVEMENTS IN LEAD-FREE BGAs ASSEMBLED WITH LEAD-BEARING  
SOLDERS

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,  
Mukta Farooq, et al.

By Ira D. Blecker  
Ira D. Blecker, Attorney  
Registration No. 29,894  
Telephone No. 845-894-2580

FORM PTO-1449 (Modified) OCT 21 2004 (37 CFR 1.905(b)) PATENT AND TRADEMARK OFFICE	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO.: FIS920040001US1	SERIAL NO.: 10/711,461
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		APPLICANT: Mukta G. Farooq et al.	
		FILING DATE: 9/20/04	GROUP:

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB- CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

		PUBLICATION NUMBER	PUBLICAITON DATE	PATENTEE			
	AL						
	AM						
	AN						
	AO						
	AP						

## FOREIGN PATENT DOCUMENTS

			PUBLICATION DATE	COUNTRY OR PATENT OFFICE	CLASS	SUB- CLASS	TRANSLATION	
		DOCUMENT NUMBER					YES	NO
	AQ	EPO 0177042 A	09.04.86	EPO				
	AR							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	AS	"Solder Joint Formation With Sn-Ag-Cu And Sn-Pb Solder BAI Pastes", Polina Snugovsky et al., Clestica International, Inc; SMTA, 12/31/2003; <a href="http://www.smta.org/knowledge/proceedings_abstract.cfm?PROCEEDING_ID=1128">www.smta.org/knowledge/proceedings_abstract.cfm?PROCEEDING_ID=1128</a>
	AT	

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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